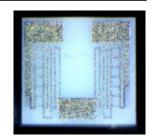


Dual Chip Resistors – PD Series

-w-Product Features

- Two resistors on a single chip area.
- Available styles are common or isolated node.
- The nature of this design lends itself to tightly matched TCR and electrical tolerance, with resistance ratios within 0.01% possible (value dependent).
- Can be used in Non-Magnetic Applications



-w-Product Specifications

Resistance Range $2\Omega - 1M\Omega$ per resistor (Silicon or Quartz) $2\Omega - 160k\Omega$ per resistor (Al₂O₃, BeO, or AlN)

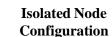




Resistance Tolerance

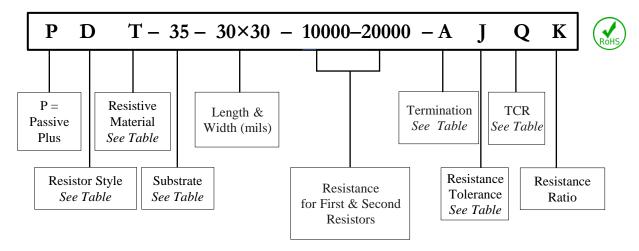
 $\pm 0.01\%$ to $\pm 20\%$ value dependent

Common Node Configuration



Standard Size 30 mil x 30 mil x 10 mil 0.03" x 0.03" x 0.01"

-w-Part Numbering



-w-Resistor Style

Code	Style
D	Common Node
I	Isolated Node

-w-Resistive Materials

Code	Material	Passivation	Sheet Resistivity (Ω/ Sq)	Abs. Tolerance	Ratio Tolerance
Т	Tantalum Nitride (TaN)	Self Passivating Ta ₂ O ₅	5 to 270	From ±0.01%	From ±0.01%
N	NiChrome (NiCr)	SiO ₂	5 to 250	From ±0.01%	From ±0.01%





Dual Chip Resistors – PD Series

-w-Substrate Materials

Code	Material	Thickness	Surface Finish	Dielectric Constant (@ 1MHz)	Coefficient of Thermal Expansion (x 10 ⁶ / °C)	Thermal Conductivity (W/m*K)
35	Alumina (Al ₂ O ₃)	0.005" - 0.010"	2μ" - 3μ"	9.9	7 (25°C to < 300°C)	26.9
28	Aluminum Nitride (AlN)	0.005" - 0.010"	6μ" - 8μ"	8.0 - 9.1	4.6 - 5.7 (25°C to < 1000°C)	170
25	Beryllium Oxide (BeO)	0.005" - 0.010"	<5μ"	6.76	9 (25°C to < 1000°C)	285
22	Silicon (Si) (with 12kÅ SiO ₂)	0.005" - 0.010"	Chemical Polish	N/A (SiO ₂ K=1.38)	2.49 - 4.44 (25°C to < 1000°C)	149 (SiO ₂ 1.38)
20	Quartz (Fused Silica)	0.005" - 0.010"	60/40 Optical Polish	3.826	0.55 (25°C to < 1000°C)	1.38

-w-Resistance Tolerance Codes

	Code	В	D	F	G	Н	J	K	L	M	Q	\mathbf{S}
Ī	Tolerance	± 0.1%	± 0.5%	± 1%	± 2%	± 3%	± 5%	± 10%	± 15%	± 20%	± 0.05%	± 0.01%

-w-Terminations

-w-Temperature Coefficient of Resistance

	To	op Side	Bot	tom Side
Code	ode Metallization Attachement Options		Metallization	Attachement Options
A	Pd/Au	Wirebond, Non-Cond. Epoxy	1	_
R	Flip Chip (Ti/Pt/Au)	Cond. Epoxy Non-Cond. Epoxy Eutectic Attach Solder	ı	-
D	Pd/Au	Wirebond Non-Cond. Epoxy	Ta/Pd/Au	Cond. Epoxy Non-Cond. Epoxy Eutectic Attach Solder

		Mat	erial
Code	TCC	Tantallum Nitride (TaN)	NiChrome (NiCr)
Q	±150 PPM/°C	Standard	
V	±100 PPM/°C	Yes	
W	±50 PPM/°C	Yes	Yes
X	±25 PPM/°C		Standard
Y	±10 PPM/°C		Yes
Z	±5 PPM/°C		Yes

-w-Resistance Ratio Codes

Code	Tolerance to	Code	Tolerance to
Coue	Other Resistors	Code	Other Resistors
G	$\pm 0.01\%$	M	±0.50%
Н	$\pm 0.05\%$	N	±1.00%
J	±0.10%	R	No Ratio
K	±0.25%		

-w-Power Handling Range by Material

Case Size	Alumina	Silicon	AlN	BeO	Quartz
mils (inches)	(35)	(22)	(28)	(25)	(20)
30 x 30 (0.030 x 0.030)	125 mW	125 mW	500 mW	1.0 W	25 mW



sales@passiveplus.com



Dual Chip Resistors – PD Series

-w-Packaging

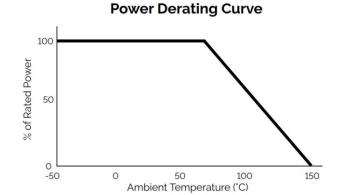
Code	Style
w	Waffle Pack
	(Standard)

Contact PPI for additional packaging options.

The standard dimensional tolerance for length and width is \pm 2 mils. The standard dimensional tolerance for thickness is \pm 1 mil.

-w-General Properties

Operating Temperature	-55°C to +150°C
Storage Temperature	-65°C to +150°C
Operating Frequency	DC to 500 MHz
Voltage Rating	100V maximum
Power Derating (See Chart at Right)	Full power up to 70°C Derated linearly to zero power at 150°C



-w-Testing

Testing Performed	Specification / Standard
Visual Inspection	MIL-PRF-55342 MIL-STD-883
Mechanical Inspection	MIL-PRF-55342
DC Resistance	MIL-PRF-55342 MIL-STD-202
Resistance Temperature Characteristics (TCR)	MIL-PRF-55342
Short Time Overload	MIL-PRF-55342
High Temperature Exposure	MIL-PRF-55342
Thermal Shock	MIL-PRF-55342 MIL-STD-202
Resistance to Bonding Exposure	MIL-PRF-55342
Wire Bonding Integrity	MIL-PRF-55342
Life Test	MIL-PRF-55342 MIL-STD-202

-w-Performance Specifications

Higher power ratings, additional sizes, and custom resistors available. Please contact sales@passiveplus.com.

